



Material Content Data Sheet



Sales Product Name	TLE7257LE			Issued	24. January 2018			
MA#	MA001224100							
Package	PG-TSON-8-1			Weight*	26.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	3.08	3.08	30848	30848
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		440	
	non noble metal	copper	7440-50-8	9.586	35.72		357182	
wire	non noble metal	iron	7439-89-6	0.236	0.88	36.65	8797	366529
	non noble metal	copper	7440-50-8	0.037	0.14	0.14	1397	1397
	plastics	epoxy resin	-	1.580	5.89		58866	
encapsulation	inorganic material	silicondioxide	60676-86-0	13.728	51.16		511508	
	organic material	carbon black	1333-86-4	0.031	0.11	57.16	1143	571517
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14241	14241
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1620	1620
glue	noble metal	silver	7440-22-4	0.279	1.04		10386	
*deviation	plastics	epoxy resin	-	0.093	0.35	1.39	3462	13848
	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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